

MOSFETs Silicon N-channel MOS (U-MOSIX-H)

# TK2R9E10PL

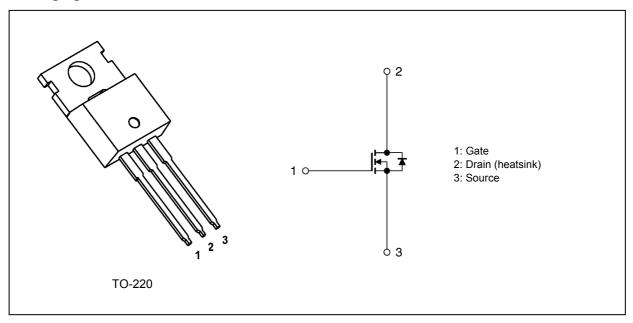
#### 1. Applications

- High-Efficiency DC-DC Converters
- Switching Voltage Regulators
- · Motor Drivers

#### 2. Features

- (1) High-speed switching
- (2) Small gate charge:  $Q_{SW} = 48 \text{ nC (typ.)}$
- (3) Small output charge:  $Q_{oss} = 164 \text{ nC (typ.)}$
- (4) Low drain-source on-resistance:  $R_{DS(ON)} = 2.4 \text{ m}\Omega$  (typ.) ( $V_{GS} = 10 \text{ V}$ )
- (5) Low leakage current:  $I_{DSS}$  = 10  $\mu A$  (max) ( $V_{DS}$  = 100 V)
- (6) Enhancement mode:  $V_{th} = 1.5 \text{ to } 2.5 \text{ V } (V_{DS} = 10 \text{ V}, I_D = 1 \text{ mA})$

#### 3. Packaging and Internal Circuit





### 4. Absolute Maximum Ratings (Note) (Ta = 25 °C unless otherwise specified)

| Characteristics                |                          |                    | Symbol           | Rating     | Unit  |
|--------------------------------|--------------------------|--------------------|------------------|------------|-------|
| Drain-source voltage           |                          |                    | $V_{DSS}$        | 100        | V     |
| Gate-source voltage            |                          |                    | $V_{GSS}$        | ±20        |       |
| Drain current (DC)             | (T <sub>c</sub> = 25 °C) | (Note 1)           | Ι <sub>D</sub>   | 100        | Α     |
| Drain current (DC)             | (Silicon limit)          | (Note 1), (Note 2) | Ι <sub>D</sub>   | 240        |       |
| Drain current (pulsed)         | (t = 100 μs)             | (Note 1)           | I <sub>DP</sub>  | 500        |       |
| Power dissipation              | (T <sub>c</sub> = 25 °C) |                    | $P_D$            | 306        | W     |
| Single-pulse avalanche energy  |                          | (Note 3)           | E <sub>AS</sub>  | 278        | mJ    |
| Single-pulse avalanche current |                          | (Note 3)           | I <sub>AS</sub>  | 86         | Α     |
| Channel temperature            |                          |                    | T <sub>ch</sub>  | 175        | °C    |
| Storage temperature            |                          |                    | T <sub>stg</sub> | -55 to 175 | °C    |
| Mounting torque                |                          |                    | TOR              | 0.6        | N · m |

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

#### 5. Thermal Characteristics

| Characteristics  | Symbol                | Max  | Unit |
|--|-----------------------|------|------|
| Channel-to-case thermal resistance (T <sub>c</sub> = 25 °C)    | R <sub>th(ch-c)</sub> | 0.49 | °C/W |
| Channel-to-ambient thermal resistance (T <sub>a</sub> = 25 °C) | R <sub>th(ch-a)</sub> | 83.3 |      |

Note 1: Ensure that the channel temperature does not exceed 175 °C.

Note 2: Limited 100 A by package capability.

Note 3:  $V_{DD}$  = 80 V,  $T_{ch}$  = 25 °C (initial), L = 29  $\mu$ H,  $I_{AS}$  = 86 A

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.



#### 6. Electrical Characteristics

### 6.1. Static Characteristics (T<sub>a</sub> = 25 °C unless otherwise specified)

| Characteristics                         | Symbol               | Test Condition                                    | Min | Тур. | Max  | Unit |
|---|----------------------|---|-----|------|------|------|
| Gate leakage current                    | I <sub>GSS</sub>     | $V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$ | _   | _    | ±0.1 | μΑ   |
| Drain cut-off current                   | I <sub>DSS</sub>     | V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V    | _   |      | 10   |      |
| Drain-source breakdown voltage          | V <sub>(BR)DSS</sub> | $I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$       | 100 |      |      | V    |
| Drain-source breakdown voltage (Note 4) | V <sub>(BR)DSX</sub> | $I_D = 10 \text{ mA}, V_{GS} = -20 \text{ V}$     | 65  | _    |      |      |
| Gate threshold voltage                  | $V_{th}$             | V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA     | 1.5 | _    | 2.5  |      |
| Drain-source on-resistance              | R <sub>DS(ON)</sub>  | $V_{GS} = 4.5 \text{ V}, I_D = 50 \text{ A}$      | _   | 2.9  | 4.1  | mΩ   |
|   |                      | $V_{GS}$ = 10 V, $I_{D}$ = 50 A                   | _   | 2.4  | 2.9  |      |

Note 4: If a reverse bias is applied between gate and source, this device enters  $V_{(BR)DSX}$  mode. Note that the drain-source breakdown voltage is lowered in this mode.

### 6.2. Dynamic Characteristics (T<sub>a</sub> = 25 °C unless otherwise specified)

| Characteristics                | Symbol           | Test Condition   | Min | Тур. | Max | Unit |
|--------------------------------|------------------|--|-----|------|-----|------|
| Input capacitance              | C <sub>iss</sub> | V <sub>DS</sub> = 50 V, V <sub>GS</sub> = 0 V, f = 1 MHz | _   | 9500 | _   | pF   |
| Reverse transfer capacitance   | C <sub>rss</sub> |  | _   | 65   | _   |      |
| Output capacitance             | C <sub>oss</sub> |  | _   | 1500 | _   |      |
| Gate resistance                | r <sub>g</sub>   | _  | _   | 2.2  | _   | Ω    |
| Switching time (rise time)     | t <sub>r</sub>   | See Fig. 6.2.1   | _   | 22   | _   | ns   |
| Switching time (turn-on time)  | t <sub>on</sub>  |  | _   | 46   | _   |      |
| Switching time (fall time)     | t <sub>f</sub>   |  | _   | 46   | _   |      |
| Switching time (turn-off time) | t <sub>off</sub> |  | _   | 147  | _   |      |

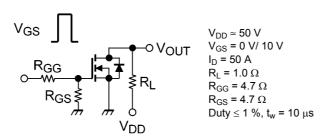


Fig. 6.2.1 Switching Time Test Circuit

### 6.3. Gate Charge Characteristics (T<sub>a</sub> = 25 °C unless otherwise specified)

| Characteristics                     | Symbol           | Test Condition  | Min | Тур. | Max | Unit |
|-------------------------------------|------------------|---|-----|------|-----|------|
| Total gate charge (gate-source plus | $Q_g$            | $V_{DD} \approx 50 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 50 \text{ A}$  | _   | 161  | _   | nC   |
| gate-drain)                         |                  | $V_{DD} \approx 50 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 50 \text{ A}$ | _   | 83   |     |      |
| Gate-source charge 1                | Q <sub>gs1</sub> | $V_{DD} \approx 50 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 50 \text{ A}$  | _   | 30   |     |      |
| Gate-drain charge                   | $Q_{gd}$         |   | _   | 37   | _   |      |
| Gate switch charge                  | $Q_{SW}$         |   | _   | 48   | _   |      |
| Output charge                       | $Q_{oss}$        | V <sub>DS</sub> = 50 V, V <sub>GS</sub> = 0 V, f = 1 MHz                  | _   | 164  | _   |      |



### 6.4. Source-Drain Characteristics (T<sub>a</sub> = 25 °C unless otherwise specified)

| Characteristics                         | Symbol                           | Test Condition                                 | Min | Тур. | Max  | Unit |
|---|----------------------------------|--|-----|------|------|------|
| Reverse drain current (pulsed) (Note 5) | I <sub>DRP</sub><br>(t = 100 μs) | _  | 1   | ı    | 500  | Α    |
| Diode forward voltage V                 |                                  | I <sub>DR</sub> = 100 A, V <sub>GS</sub> = 0 V |     |      | -1.5 | V    |
| Reverse recovery time                   | t <sub>rr</sub>                  | I <sub>DR</sub> = 25 A, V <sub>GS</sub> = 0 V, | _   | 75   | _    | ns   |
| Reverse recovery charge                 | Q <sub>rr</sub>                  | -dI <sub>DR</sub> /dt = 100 A/μs               |     | 150  | 1    | nC   |

Note 5: Ensure that the channel temperature does not exceed 175 °C.

### 7. Marking

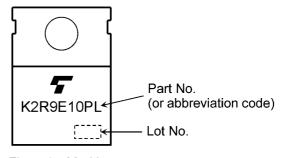


Fig. 7.1 Marking



#### 8. Characteristics Curves (Note)

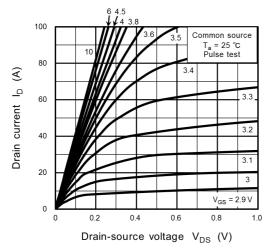


Fig. 8.1 I<sub>D</sub> - V<sub>DS</sub>

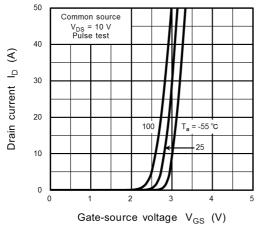


Fig. 8.3 I<sub>D</sub> - V<sub>GS</sub>

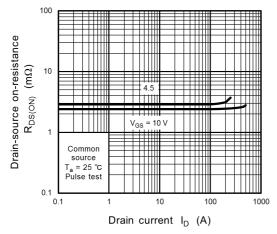


Fig. 8.5 R<sub>DS(ON)</sub> - I<sub>D</sub>

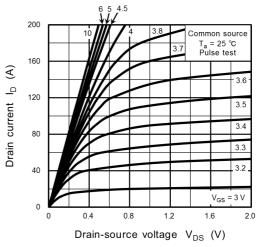


Fig. 8.2 I<sub>D</sub> - V<sub>DS</sub>

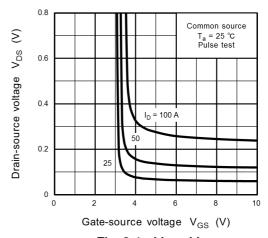


Fig. 8.4 V<sub>DS</sub> - V<sub>GS</sub>

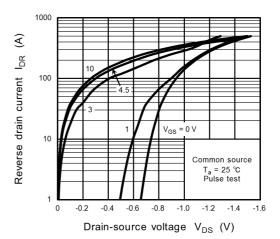


Fig. 8.6  $I_{DR}$  -  $V_{DS}$ 



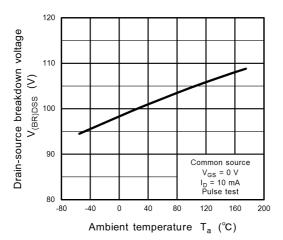


Fig. 8.7 V<sub>(BR)DSS</sub> - T<sub>a</sub>

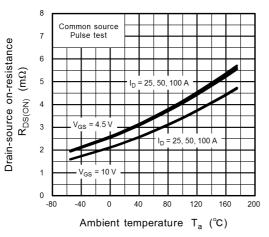


Fig. 8.9 R<sub>DS(ON)</sub> - T<sub>a</sub>

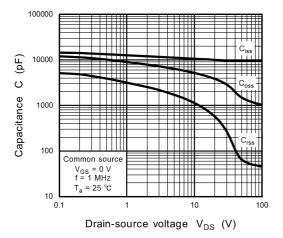


Fig. 8.11 Capacitance - V<sub>DS</sub>

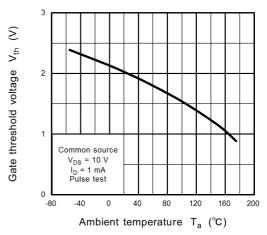


Fig. 8.8 V<sub>th</sub> - T<sub>a</sub>

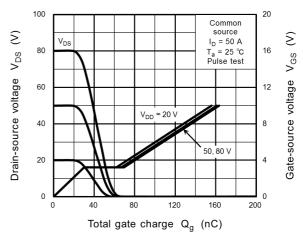


Fig. 8.10 Dynamic Input/Output Characteristics

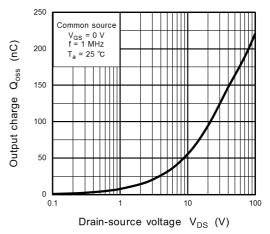


Fig. 8.12 Qoss - VDS



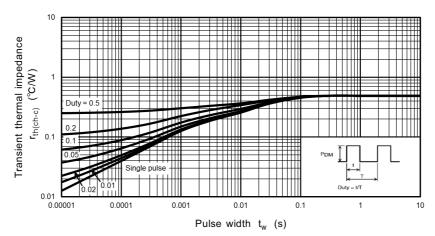
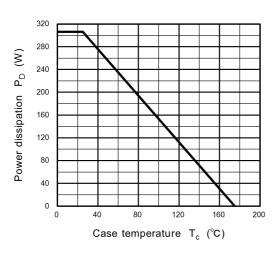


Fig. 8.13 r<sub>th</sub> - t<sub>w</sub> (Guaranteed Maximum)



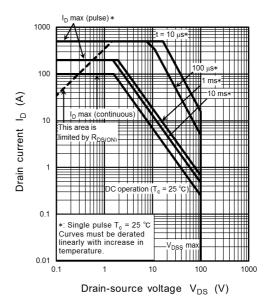


Fig. 8.14 P<sub>D</sub> - T<sub>c</sub> (Guaranteed Maximum)

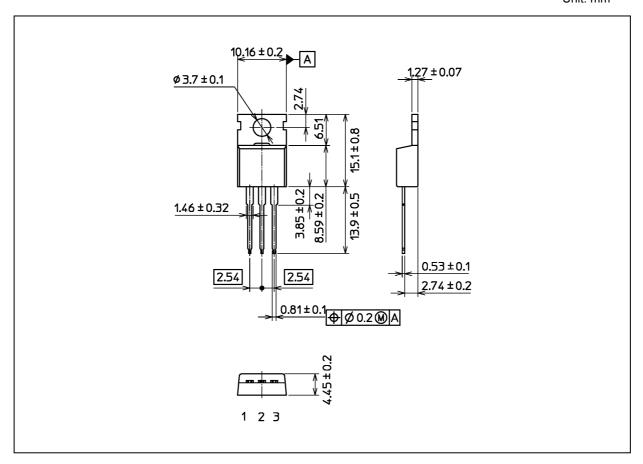
Fig. 8.15 Safe Operating Area (Guaranteed Maximum)

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



### **Package Dimensions**

Unit: mm



Weight: 1.93 g (typ.)

| Package Name(s)  |
|------------------|
| TOSHIBA: 2-10X1A |
| Nickname: TO-220 |



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